TABLE 4. 270°C solder dip cycle testing of oxide alternative in combination with new developed pre-

and post-treatment chemistry.				
EXPERIMENTAL TRIA	L #1	#2	#3	#4
Microetch	Reference	New-I	New-II	New-I

New - I

Reference

New - I

New - I

Reference

None

10

Reference

Reference

Reference

Alkaline Cleaner

Cycles to Delamination

**AlphaPREP** 

Post Dip

New - II

Reference

None

10